Serial Number: 10/673,605

Filing Date: September 29, 2003

Title: DIFFUSION BARRIER LAYER FOR LEAD FREE PACKAGE SUBSTRATE

Assignee: Intel Corporation

REMARKS

Claims 20-27 have been canceled, and claims 31-39 have been added. No claims have been amended.

In response to the Restriction Requirement mailed June 30, 2004, Applicants hereby elect, without traverse, Group I (claims 1-19 and 28-30). Applicants reserve the right to reintroduce the non-elected claims 20-27 in one or more divisional applications at a later date.

The Examiner is invited to telephone Applicants' attorney at (612) 373-6977 to facilitate the prosecution of this application. If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

KUM FOO LEONG ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

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Dkt: 884.A68US1 (INTEL)

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By

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 30 day of July, 2004. Signature Kacia Lel

Name